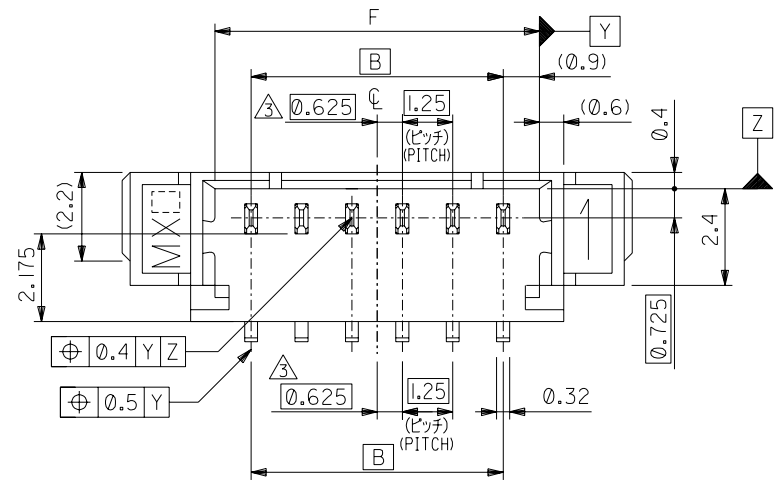
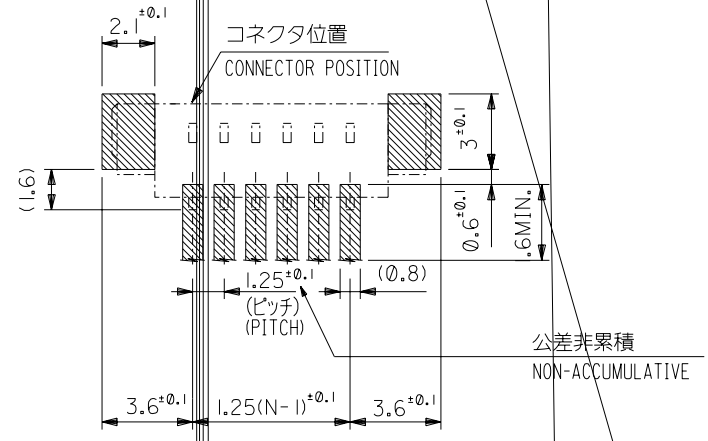


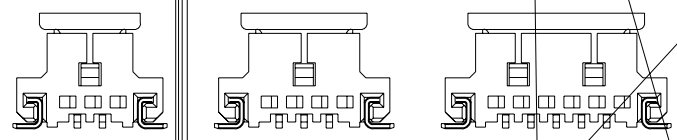
DWG. NO. SD-53398-034



カバーなしの場合 (53398-**19)
IN CASE OF WITHOUT COVER



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



2極 2 CKT.
3極 3 CKT.
4極以上 OVER 4 CKT.

ロック形状図
LOCK CONFIGURATION

NOTES

△5 ロック窓は、2, 3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

DO NOT SCALE DRAWING

RELEASED '04/02/12
12004-2404
Y.SAKIYAMA
M.SASAO
M.SASAO

DESCRIPTION

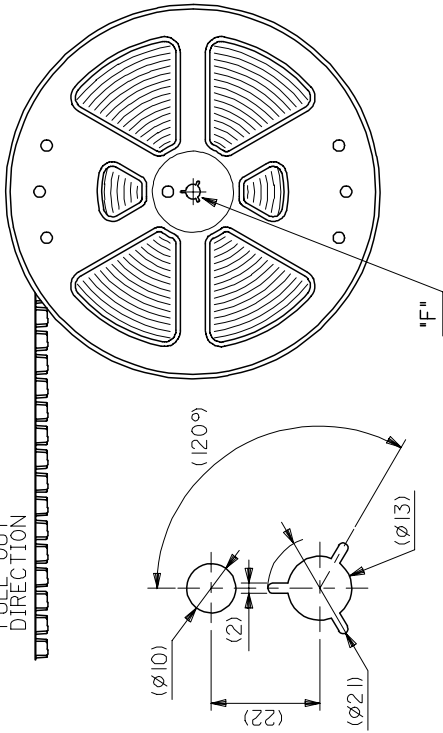
SEE NOTES

GENERAL TOLERANCES:
(UNLESS SPECIFIED)

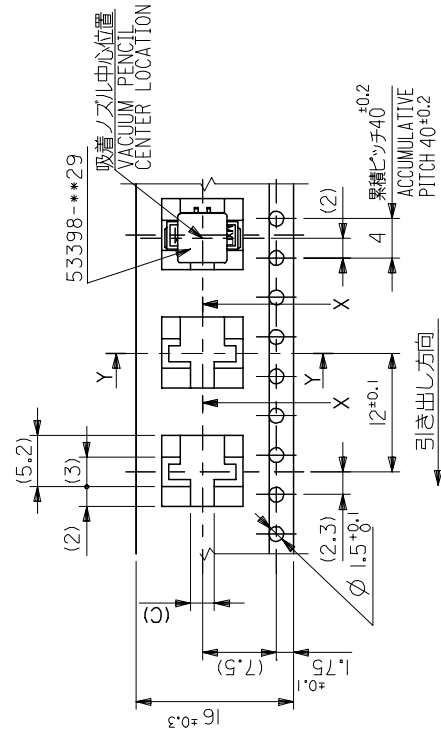
MODEL NO.	53398-**29	DIMENSIONS:	SHT	REV
SCALE				REVISE ON CAD ONLY
DRAWN BY & DATE	Y.SAKIYAMA '04/02/12	TITLE:	1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-	
M.SASAO	'04/02/12			
M.SASAO	'04/02/12			
CAD FILENAME	SD-53398-034.S02	MATERIAL NO.	DRAWING NO.	SHEET NO.
		SEE CHART	SD-53398-034	2 OF 2

SD-53398-034.S02

引き出し方向
PULL OUT
DIRECTION

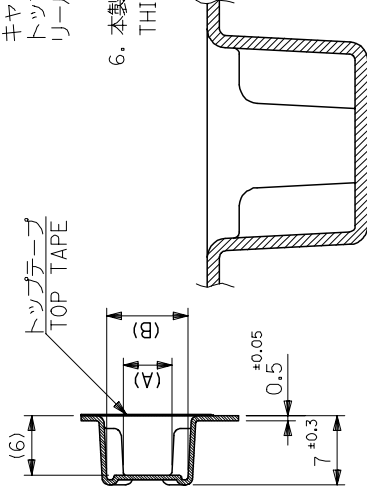
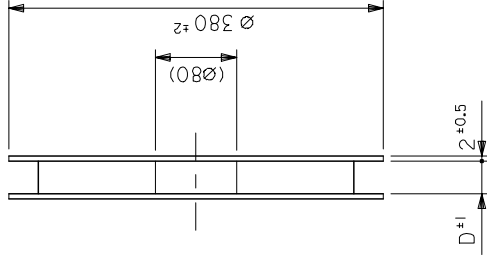


DETAIL "F"



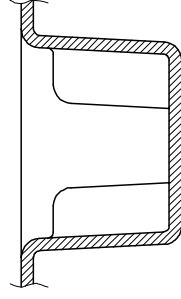
引き出し方向
PULL OUT DIRECTION

16幅テープ
(TAPE WIDTH:16)

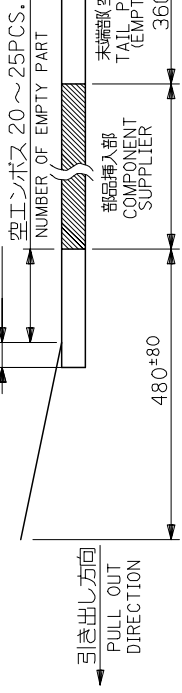


SECT:Y-Y

SECT:X-X



- NOTES
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
 - リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度: 0.6±0.35N(60±35gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.6±0.35N(60±35gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

剥離方向
PEEL OFF
DIRECTION

10°

引き出し方向
PULL OUT
DIRECTION

- 53398-***29の詳細寸法については図面 SD-53398-034 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53398-034.

材料 (MATERIAL)

キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

- 本製品は 53398-***80 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***80.

32	33.4	14.95	20.75	17.05	53398-1267	12
		9.95	15.75	12.05	53398-0867	8
		8.7	14.5	10.8	53398-0767	7
24	25.4	7.45	13.25	9.55	53398-0667	6
		6.2	12	8.3	53398-0567	5
		4.95	10.75	7.05	53398-0467	4
		3.7	9.5	5.8	53398-0367	3
16	17.4	2.45	8.25	4.55	53398-0267	2

キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS
MM ONLY	SCALE	DESIGN UNITS	METRIC	THIRD ANGLE	PROJECTION	

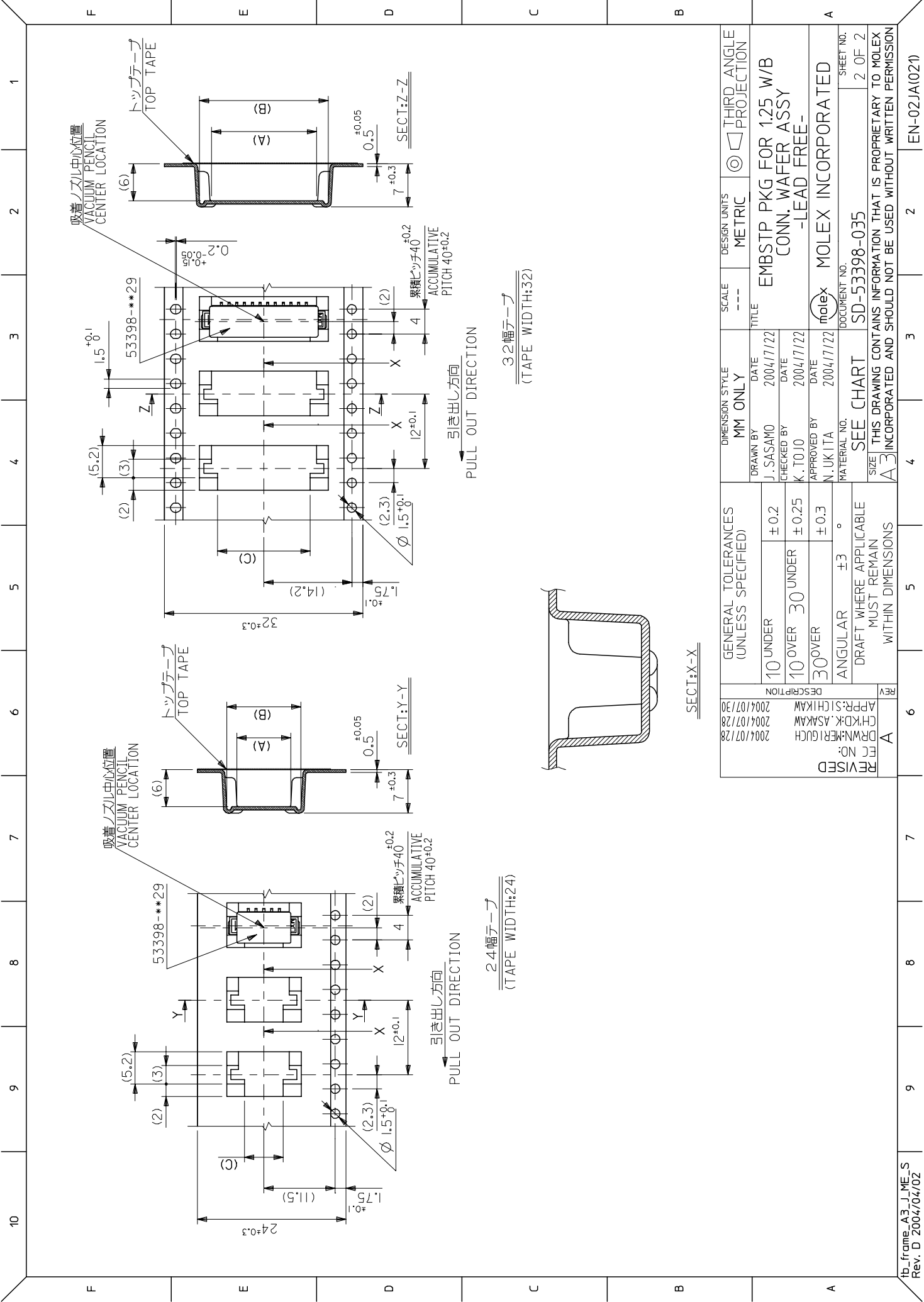
DRAWN BY	DATE	TITLE
J. SASAKI	2004/11/22	EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-

CHECKED BY	DATE
K. TOJO	2004/11/22

APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.
N. UKITA	2004/11/22	MOLEX INCORPORATED	SD-53398-035

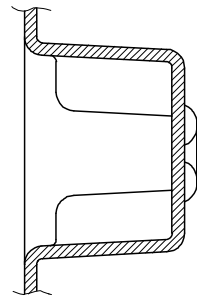
SEE CHART	SIZE	SHEET NO.
	A3	1 OF 2

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



2.4幅テープ
(TAPE WIDTH:24)

3.2幅テープ
(TAPE WIDTH:32)



SECT: X-X

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
10 UNDER	± 0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-		
10 OVER	30 UNDER	CHECKED BY K. TOJO	DATE 2004/7/22	DOCUMENT NO. MOLEX INCORPORATED		
30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2004/7/22	SHEET NO. 2 OF 2		
ANGULAR	± 3 °	MATERIAL NO. SEE CHART		SD-53398-035		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						
REVISED	EC NO.	DESCRIPTION		SIZE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX A3 INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
A		APPROVALS	2004/07/28	2004/07/28	2004/07/28	
		CHK'D: K. ASAKAWA				
		APPR: S. ICHIKAWA				